OMB No. 3117-0016/USITC No. 03-4-2043; Expiration Date: 6/30/05
(No response is required if currently valid OMB control number is not displayed)

FOREIGN PRODUCERS'/EXPORTERS' QUESTIONNAIRE
DRAMS AND DRAM MODULES FROM KOREA

Return completed questionnaire to:

UNITED STATES INTERNATIONAL TRADE COMMISSION
Office of Investigations, Room 615
500 E Street, SW, Washington, DC 20436

So as to be received by the Commission by no later than May 9, 2003

The information called for in this questionnaire is for use by the United States International Trade Commission in connection with its countervailing duty investigation concerning DRAMs and DRAM modules from Korea (inv. No. 701-TA-431 (Final)). The information requested in the questionnaire is requested under the authority of the Tariff Act of 1930, title VII.

Name of firm ________________________________

Address ________________________________

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World Wide Web address ________________________________

Has your firm produced or exported DRAMs or DRAM modules (as defined in the instruction booklet) at any time since January 1, 2000?

☐ **NO** (Sign the certification below and promptly return only this page of the questionnaire to the Commission)

☐ **YES** (Read the instruction booklet carefully, complete all parts of the questionnaire, sign the certification, and return the entire questionnaire to the Commission)

CERTIFICATION

I certify that the information herein supplied in response to this questionnaire is complete and correct to the best of my knowledge and belief and understand that the information submitted is subject to audit and verification by the Commission.

By signing this certification I also grant consent for the Commission, and its employees and contract personnel, to use the information provided in this questionnaire and throughout this investigation in any other import-injury investigations conducted by the Commission on the same or similar merchandise. (If you do not consent to such use, please note the certification accordingly.)

I acknowledge that information submitted in this questionnaire response and throughout this investigation may be used by the Commission, its employees, and contract personnel who are acting in the capacity of Commission employees, for developing or maintaining the records of this investigation or related proceedings for which this information is submitted, or in internal audits and investigations relating to the programs and operations of the Commission pursuant to 5 U.S.C. Appendix 3. I understand that all contract personnel will sign non-disclosure agreements.

____
Name and Title of Authorized Official

____
Date

____
Signature of Authorized Official

(   ) ________________
Phone

(   ) ________________
Fax

____
E-mail address

PART I.--GENERAL QUESTIONS

The questions in this questionnaire have been reviewed with market participants to ensure that issues of concern are adequately addressed and that data requests are sufficient, meaningful, and as limited as possible. Public reporting burden for this questionnaire is estimated to average 40 hours per response, including the time for reviewing instructions, searching existing data sources, gathering the data needed, and completing and reviewing the questionnaire. Send comments regarding the accuracy of this burden estimate or any other aspect of this collection of information, including suggestions for reducing the burden, to the Office of Investigations, U.S. International Trade Commission, 500 E Street, SW, Washington, DC 20436.

I-1. Please report below the actual number of hours required and the cost to your firm of preparing the reply to this questionnaire and completing the form.

________ hours ________ dollars

I-2. Provide the name and address of establishment(s) covered by this questionnaire (see page 3 of the instruction booklet for reporting guidelines). If your firm is publicly traded, please specify the stock exchange and trading symbol.

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I-3. Please provide the names and addresses of the **FIVE** largest U.S. importers of your firm's DRAMs and DRAM modules in 2002.

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I-4. Does your firm or any related firm produce, have the capability to produce, or have any plans to produce DRAMs or DRAM modules in the United States or other countries?

☐ No ☐ Yes--Please name the firm(s) and country(ies) below and, if U.S. producer(s), ensure that they complete the Commission's producer questionnaire (contact Mary Messer (202-205-3193) for copies of that questionnaire).

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PART I.–GENERAL QUESTIONS–*Continued*

I-5. Does your firm or any related firm import or have any plans to import DRAMs or DRAM modules into the United States?

☐ No ☐ Yes--Please name the firm(s) below and ensure that they complete the Commission's importer questionnaire (contact Mary Messer (202-205-3193) for copies of that questionnaire).

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PART II.--TRADE AND RELATED INFORMATION

II-1. Does your firm have any plans to add, expand, curtail, or shut down production capacity and/or production of DRAMs or DRAM modules in Korea?

☐ No ☐ Yes--Please describe those plans, including planned dates and capacity/ production quantities involved, and the reason(s) for such change(s). If the plans are to add or expand capacity or production, list (in descending order of importance) the markets (countries) to which such additional capacity or production would be directed.

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II-2. What percentage of your firm's total sales in its most recent fiscal year was represented by sales of DRAMs and DRAM modules? ___ Percent

II-3. (a) Does your firm produce other products (e.g., logic devices, SRAM modules, flash memory, etc.) on the same equipment and machinery used in the production of DRAMs and DRAM modules? Please distinguish between equipment used to produce DRAMs with a density of 64 meg and lower, and equipment used to produce DRAMs with a density of 128 meg and higher.

☐ No ☐ Yes--Please list these product(s) and provide the share of your firm's total net sales (in percent) accounted for by these product(s) in its most recent fiscal year and the basis you used to allocate capacity in question II-12 to DRAMs and DRAM modules.

Product(s)	*Share of sales*	*Basis for allocation of capacity data*

(b) Please provide the share (in percent) of your total wafer starts accounted for by DRAM wafers (regardless of density) in each of the following periods:

2000 ______; 2001 ______; 2002 ______; Jan.-Mar. 2002 ______; Jan.-Mar. 2003 ______

PART II.--TRADE AND RELATED INFORMATION–*Continued*

(c) Please provide the share (in percent) of your total assembly capability accounted for by cased DRAMs (regardless of density) in each of the following periods:

2000 ______; 2001 ______; 2002 ______; Jan.-Mar. 2002 ______; Jan.-Mar. 2003 ______

II-4. Has your firm maintained any inventories of DRAMs or DRAM modules in the United States (not including inventories held by firms identified in questions I-3, I-4, or I-5 above[1]) since 2000?

☐ No ☐ Yes--Report the quantity (in billions of bits) of such **end-of-period** inventories below.

Item	2000	2001	2002	Mar. 2002	Mar. 2003
Uncased DRAMs					
Cased DRAMs					
DRAM modules					

II-5. Does your firm sell DRAMs or DRAM modules over the internet?

☐ No ☐ Yes–Please describe, noting the estimated percentage of your firm's total sales of DRAMs and DRAM modules in 2002 accounted for by internet sales.

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II-6. Describe the significance of the U.S. antidumping duty order covering imports of other-than-Samsung Korean DRAMs $ 1-Meg and DRAM modules containing any DRAMs $ 1-Meg that was in effect from May 10, 1993, until October 5, 2000, in terms of its effect, either directly or indirectly, on your firm's exports, shipments, and inventories while the order was in effect and any effects of resulting from its termination. Use additional pages as necessary.

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[1] Such firms will report inventories in the Commission's importer or producer questionnaire.

PART II.--TRADE AND RELATED INFORMATION–*Continued*

II-7. Are the DRAMs or DRAM modules exported by your firm subject to antidumping or subsidy findings or remedies or subject to ongoing antidumping or subsidy investigations in any WTO-member countries?

☐ No ☐ Yes--List the products(s), countries affected, and the date of such findings/remedies or status of ongoing investigations.

Product	***Country***	***Date or Status***

II-8. (a) Do you always know the country of fabrication for your purchases and internal transfers of uncased DRAMs?

☐ No ☐ Yes

(b) Do you always know the identity of the fabricating firm for your purchases and internal transfers of uncased DRAMs?

☐ No ☐ Yes

II-9. (a) Do you always know the country of fabrication and the country of assembly for your purchases and internal transfers of cased DRAMs?

Uncased DRAM fabrication: ☐ No ☐ Yes
Cased DRAM assembly: ☐ No ☐ Yes

(b) Do you always know the identity of the fabricating firm for your purchases and internal transfers of cased DRAMs?

Uncased DRAM fabrication: ☐ No ☐ Yes

II-10. (a) Do you always know the country of fabrication and the country of assembly for your purchases and internal transfers of DRAM modules?

Uncased DRAM fabrication: ☐ No ☐ Yes
Cased DRAM assembly: ☐ No ☐ Yes
DRAM module assembly: ☐ No ☐ Yes

(b) Do you always know the identity of the fabricating firm for your purchases and internal transfers of DRAM modules?

Uncased DRAM fabrication: ☐ No ☐ Yes

II-11. Please identify each country in which your firm or a related firm performs the following DRAM operations:

Operation	**Countries**
Uncased DRAM fabrication	
Cased DRAM assembly	
DRAM module assembly	

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-12. **ALL DRAMS**.--For your Korean establishment(s) wherein DRAM wafers are fabricated (UNCASED DRAMS), assembled (CASED), and/or assembled into modules, report the average-of-period full production capabilities (i.e., capacity--see definitions in instructions booklet). In reporting the capacity and wafer starts requested below for UNCASED DRAMS, please consider the capacity utilization (i.e., wafer starts divided by capacity) experienced by your Korean establishments wherein DRAM wafers are fabricated. Also, estimate for each period the probe yield (i.e., the percentage of usable die per wafer). For CASED DRAMS and DRAM MODULES, please consider the capacity utilization (i.e., assembly divided by assembly capacity) of your DRAM and DRAM module assembly facilities.

Item	Calendar years			January-March		Projections	
	2000	2001	2002	2002	2003	2003	2004
UNCASED DRAMS:[1] Average capacity[2] (*1,000 8-inch-equivalent wafers*)							
Wafer starts (*1,000 8-inch-equivalent wafers*)							
Probe yield (*percent*)							
CASED DRAMS: Average capacity[3] (*1,000 units*)							
Assembly[4] (*1,000 units*)							
DRAM MODULES: Average capacity[5] (*1,000 units*)							
Assembly (*1,000 units*)							

[1] Report your capacity and production on an 8-inch-equivalent wafer basis. However, indicate the size(s) (in inches) of silicon wafers actually used by your firm in the production of DRAMs.

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[2] The average capacity reported is based on operating ______ hours per week, ______ weeks per year. Briefly explain assumptions made and methods used in calculating the estimates reported above for practical capacity to fabricate DRAM wafers. Also explain any changes in reported capacity. Use additional pages as necessary. ________

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[3] The average capacity reported is based on operating ______ hours per week, ______ weeks per year. Briefly explain assumptions made and methods used in calculating the estimates reported above for average capacity to assemble DRAMs. Also explain any changes in reported capacity. Use additional pages as necessary. ____________

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[4] The data reported for all DRAMs assembled should equal the totals of production for all densities of all cased DRAMs reported in **question II-14**. If data do not reconcile, please explain, using additional pages as necessary. ____

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[5] The average capacity reported is based on operating ______ hours per week, ______ weeks per year. Briefly explain assumptions made and methods used in calculating the estimates reported above for average capacity to assemble DRAM modules. Also explain any changes in reported capacity. Use additional pages as necessary. _____

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PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-13. **UNCASED DRAMS FABRICATED IN KOREA.--**Report your firm's production, shipments, and inventories related to the production of uncased DRAMs in your Korean establishment(s) during the specified periods. **Report separately for each density of DRAM your firm produces, photocopying this page as necessary. Identify the density reported on each page by checking the appropriate box.** (See definitions in the instruction booklet.)

☐ 16 Meg ☐ 64 Meg ☐ 128 Meg ☐ 256 Meg ☐ 512 Meg ☐ Other (specify density ______________________)

Quantity (*in 1,000 units*)

Item	Calendar years			January-March		Projections	
	2000	2001	2002	2002	2003	2003	2004
Beginning-of-period inventories							
Production[1]							
SHIPMENTS: **Home-market shipments:** Company transfers/ internal consumption for making cased DRAMs							
Other company transfers/ internal consumption (identify the nature of the transfers/consumption: ______________________)							
Home-market commercial shipments							
EXPORT SHIPMENTS TO-- **The United States:** To foreign affiliates							
To other firms							
Other markets:[2] To foreign affiliates							
To other firms							
End-of-period inventories[3]							

[1] Reported production should include only usable units (i.e., net of any losses that occur during wafer fabrication and sorting).

[2] Identify your principal export markets: ____

[3] Reconciliation of data.--Please note that the **quantities** reported above should reconcile as follows: beginning-of-period inventories, plus production, less total shipments, equals end-of-period inventories. Do the data reported reconcile?

☐ Yes ☐ No--Please explain: ____

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-14. **CASED DRAMS ASSEMBLED IN KOREA.--**Report your firm's assembly, shipments, and inventories related to the assembly of cased DRAMs in your U.S. establishment(s) during the specified periods. (See definitions in the instruction booklet.) **Report separately for each density of DRAM your firm assembles, by the location of the fabrication of the dice, photocopying this page as necessary. Identify: (1) the density, and (2) the dice fabrication location reported on each page by checking one box per category below.**

1) Density: ☐ 16 Meg ☐ 64 Meg ☐ 128 Meg ☐ 256 Meg ☐ 512 Meg ☐ Other (specify density: ____________________)

2) Dice fabrication location: ☐United States ☐Korea (Samsung) ☐Korea (other firms) ☐Other locations (specify: ______________)

Quantity (*in 1,000 units*)

Item	Calendar years			January-March		Projections	
	2000	2001	2002	2002	2003	2003	2004
Beginning-of-period inventories							
Production (assembly):[1]							
SHIPMENTS: **Home-market shipments:** Company transfers/ internal consumption for making DRAM modules							
Other company transfers/ internal consumption (identify the nature of the transfers/consumption: ____________________)							
Home-market commercial shipments							
EXPORT SHIPMENTS TO-- **The United States:** To foreign affiliates							
To other firms							
Other markets:[2] To foreign affiliates							
To other firms							
End-of-period inventories[3]							

[1] Reported production should include only usable units (i.e., net of any losses that occur during assembly and testing). In addition, reported production should include assembly of all dice, whether internally transferred or imported or otherwise purchased.

[2] Identify your principal export markets: ____

[3] Reconciliation of data.--Please note that the **quantities** reported above should reconcile as follows: beginning-of-period inventories, plus production, less total shipments, equals end-of-period inventories. Do the data reported reconcile?

☐ Yes ☐ No--Please explain: ____

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-15. **DRAM MODULES ASSEMBLED IN KOREA.--**Report your firm's assembly, shipments, and inventories related to the assembly of DRAM modules in your Korean establishment(s) during the specified periods. (See definitions in the instruction booklet.) **Report separately for each dice fabrication location/cased DRAM assembly location combination. Photocopy this page as necessary, checking one box per category for the: (1) dice fabrication location, and (2) cased DRAM assembly location reported on each page.**

1) Dice fabrication location: ☐ United States ☐ Korea ☐ Other locations (specify: ______)

2) Cased DRAMs assembly location: ☐United States ☐Korea (Samsung) ☐Korea (other firms) ☐Other locations (specify: ______)

Quantity (*in billion bits*)

	Calendar years			**January-March**		**Projections**	
Item	**2000**	**2001**	**2002**	**2002**	**2003**	**2004**	**2005**
Beginning-of-period inventories							
Production (assembly):[1]							
SHIPMENTS: **Home-market shipments:** Company transfers/ internal consumption (identify the nature of the transfers/consumption: ______)							
Home-market commercial shipments							
EXPORT SHIPMENTS TO-- **The United States:** To foreign affiliates							
To other firms							
Other markets:[2] To foreign affiliates							
To other firms							
End-of-period inventories[3]							

[1] Reported only usable modules (i.e., net of any losses that occur during assembly and testing).

[2] Identify your principal export markets: ______

[5] Reconciliation of data.--Please note that the **quantities** reported above should reconcile as follows: beginning-of-period inventories, plus production, less total shipments, equals end-of-period inventories. Do the data reported reconcile?

☐ Yes ☐ No--Please explain: ______

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-16. (a) In the following table, please estimate the shares (in percent) of the quantity of your 2002 Korean production of DRAMs and DRAM modules, by DRAM type and by location of dice fabrication.

	Dice fabricated in--				
	United States	Korea		Other sources	All sources
Type of DRAM		Samsung	Other		
Standard DRAMs, including extended data out (EDO), fast page, synchronous, and double data rate					
Rambus					
Other DRAM types, including video (VRAM), synchronous graphics (SGRAM), windows (WRAM), and other (please specify type(s)): ________________ ________________________________ ________________________________					
Total, all DRAMs					100.0%

(b) In reference to the data provided in II-16a, please note general changes (if any) in your DRAM product mix or source mix that transpired during January 2000-March 2003.

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II-17. (a) **DRAMS AND DRAM MODULES**.–Please provide the **value** (in thousands of U.S. dollars) of your firm's export shipments to non-U.S. markets (for which quantities were provided in questions II-13 to II-15 at pages 7 to 9). Please report separately for export shipments to the EU and to other non-U.S. export markets.

Value (*in 1,000 U.S. dollars*)							
	Calendar years			**January-March**		**Projections**	
Item	**2000**	**2001**	**2002**	**2002**	**2003**	**2004**	**2005**
EXPORT SHIPMENTS TO-- **The EU:** To foreign affiliates							
To other firms							
Other non-U.S. markets: To foreign affiliates							
To other firms							

(b) Please note any differences in your DRAM product mix that is exported to the EU with that exported to the United States, indicating total values of any product(s) shipped to the EU that are NOT shipped to the United States for the periods specified in II-17(a).

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PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-18. Complete the following table showing the line geometry (in microns) and wafer starts for each of your fabs for January 2000 through March 2003. Also, please indicate wafer size. If the geometry changed for a fab during a year, indicate the date of the change. If at a given time a fab was operating with two or more line geometries, indicate for each year the number of wafers processed at each geometry. Photocopy this page as necessary.

	2000	2001	2002	Jan.-Mar. 2002	Jan.-Mar. 2003
Example only Fab location/ name	6-inch wafers/ 0.35/ 130,000	6-inch/ 0.35/ 70,000 8-inch / 0.25/ 75,000 (June 10)	8-inch/ 0.25/ 150,000 8-inch/ 0.22/ 60,000 (July 1)	8-inch/ 0.25/ 70,000	8-inch/ 0.22/ 90,000 8-inch/ 0.18/ 30,000 (March 3)
Fab 1 geometry					
Fab 2 geometry					
Fab 3 geometry					
Fab 4 geometry					
Fab 5 geometry					

II-19. Please indicate the number of wafers of each density of DRAMs produced and the average number of dice per wafer prior to the probe stage, for calendar 2000 through 2002 plus the two interim periods.

Density	2000	2001	2002	Jan.-Mar. 2002	Jan.-Mar 2003
64 Megabit	wafers	wafers	wafers	wafers	wafers
	dice/wafer	dice/wafer	dice/wafer	dice/wafer	dice/wafer
128 Megabit	wafers	wafers	wafers	wafers	wafers
	dice/wafer	dice/wafer	dice/wafer	dice/wafer	dice/wafer
256 Megabit	wafers	wafers	wafers	wafers	wafers
	dice/wafer	dice/wafer	dice/wafer	dice/wafer	dice/wafer
512 Megabit	wafers	wafers	wafers	wafers	wafers
	dice/wafer	dice/wafer	dice/wafer	dice/wafer	dice/wafer

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-20. Please report the approximate date your firm began selling each of the following devices in commercial quantities in the U.S. market. If your answer differs by customer type, please explain

128 Megabit SDRAMs: ____________________

256 Megabit SDRAMs: ____________________

Double Data Rate SDRAMs: ____________________

1 Gigabit SDRAMs: ____________________